ABSTRACT

SINGLE WAFER IN-SITU DRY CLEAN AND SEASONING FOR PLASMA ETCHING PROCESS

A new method is provided for the cleaning and seasoning of a Plasma Etch chamber. The wafer that is to be processed by the chamber is inserted into the chamber. The process of plasma clean is first performed on the Plasma Etch Chamber followed by a seasoning process of the Plasma Etch Chamber. The wafer is processed (etched) and removed from the chamber after the etch process has been completed. The cycle is then repeated starting with the step of loading the wafer into the plasma etch chamber followed by plasma clean and chamber seasoning of the plasma etch chamber.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)